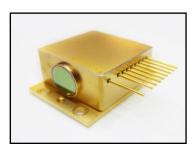
# 4.55 μm DISTRIBUTED FEEDBACK (DFB) QCL





## HIGH HEAT LOAD (HHL) PACKAGE

#### **O**VERVIEW

- Thermo-electrically cooled. External heat sink still required.
- Sealed in a nitrogen-purged atmosphere.
- Package dimensions (approx): 1.75 x 1.25 x 0.72 in (excluding pins).

### LASER SPECIFICATIONS

		Specs	Units
Process		DFB	
Oper. Temperature		15 – 45	°C
Facet Coating	Front	None	
	Back	HR	

## **ELECTRO-OPTICAL CHARACTERIZATION**

		Specs	Units
Driving Conditions	Operation Mode	CW	
	Temperature	15	°C
Electrical	Thresh. Current	0.12	Α
	Max. Current	0.18	Α
	Thresh. Voltage	12.5	V
	Max. Voltage	13.4	V
	Laser Efficiency	1.8	%
Optical	Max. Power Output	42.9	mW
	Center Wavelength	4.55	μm

## SPECTRAL CHARACTERIZATION AND BEAM QUALITY

		Specs	Units
Driving Conditions	Operation Mode	CW	
Wavelength Tuning	Temperature	0.35	nm/K
	Current	102.1	nm/A
SMSR		30	dB
Beam Profile	Full Beam Waist	3.02	mm
	M <sup>2</sup>	1.42	